

PATENT COOPERATION TREATY

PCT

INTERNATIONAL SEARCH REPORT

(PCT Article 18 and Rules 43 and 44)

Applicant's or agent's file reference SC0704EM/PCT	FOR FURTHER ACTION <small>see Notification of Transmittal of International Search Report (Form PCT/ISA/220) as well as, where applicable, item 5 below.</small>	
International application No. PCT/EP 99/ 04291	International filing date (day/month/year) 21/06/1999	(Earliest) Priority Date (day/month/year) 27/06/1998
Applicant MOTOROLA GMBH et al.		

This International Search Report has been prepared by this International Searching Authority and is transmitted to the applicant according to Article 18. A copy is being transmitted to the International Bureau.

This International Search Report consists of a total of 3 sheets



It is also accompanied by a copy of each prior art document cited in this report.

1. Basis of the report

- a. With regard to the **language**, the international search was carried out on the basis of the international application in the language in which it was filed, unless otherwise indicated under this item



the international search was carried out on the basis of a translation of the international application furnished to this Authority (Rule 23 1(b)).

- b. With regard to any **nucleotide and/or amino acid sequence** disclosed in the international application, the international search was carried out on the basis of the sequence listing :



contained in the international application in written form.



filed together with the international application in computer readable form



furnished subsequently to this Authority in written form



furnished subsequently to this Authority in computer readable form



the statement that the subsequently furnished written sequence listing does not go beyond the disclosure in the international application as filed has been furnished.



the statement that the information recorded in computer readable form is identical to the written sequence listing has been furnished

2.



Certain claims were found unsearchable (See Box I).

3.



Unity of invention is lacking (see Box II)

4. With regard to the **title**,



the text is approved as submitted by the applicant.



the text has been established by this Authority to read as follows:

5. With regard to the **abstract**,



the text is approved as submitted by the applicant.



the text has been established, according to Rule 38.2(b), by this Authority as it appears in Box III. The applicant may, within one month from the date of mailing of this international search report, submit comments to this Authority.

6. The figure of the **drawings** to be published with the abstract is Figure No.



as suggested by the applicant.



because the applicant failed to suggest a figure.



because this figure better characterizes the invention.

1



None of the figures.

10/031296

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: : Date: February 22, 2000
Markos Triantafyllou et al. : Examining Group: Not Assigned
Serial No.: Not Assigned :
Filed: February 22, 2000 : Examiner: Not Assigned
For: **ELECTRONIC PACKAGE ASSEMBLY**

PRELIMINARY AMENDMENT

HONORABLE ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

SIR:

This preliminary amendment is to put the above-identified application in better condition for allowance. Please consider the above-identified patent application in view of the amendments and remarks presented hereinafter.

Please amend the claims as follows:

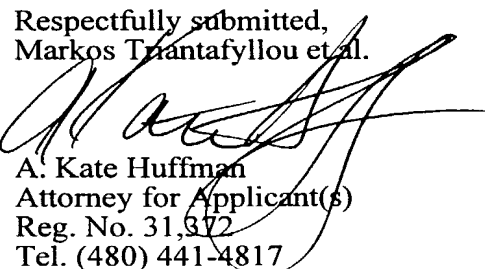
In Claim 6, Line 32, delete "any preceding claim" and insert --claim 1--.
In Claim 7, Line 35, delete "any preceding claim" and insert --claim 1--.
In Claim 8, Line 1, delete "any preceding claim" and insert --claim 1 --.

REMARKS

In view of the above, it is believed that the application is now in better condition for favorable consideration on its merits.

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ELECTRONIC PACKAGE ASSEMBLY

Field of the Invention

- 5 This invention relates to an electronic package assembly and preferably but not exclusively to an electronic package assembly incorporating a power transistor.

Background of the Invention

- 10 In many electronic applications, particularly in automotive applications, power and logic devices are used in conjunction with each other, to perform a single function.

For example, an electric motor for operating an automatic sunroof or a window of a vehicle is typically actuated by a high-sided switch formed by power transistors. In order
15 to reduce power consumption, the high-sided switch is ideally placed as close as possible to the electric motor, thus keeping the length of high current paths to a minimum and hence reducing unnecessary power losses.

Typically the driver of a vehicle may prefer to operate a separate switch on the dashboard
20 of the vehicle, which then sends a (low-power) signal to the high-sided switch, in order to actuate it. Therefore a certain amount of logic circuitry is required, preferably at the high-sided switch, in order to control the actuation and other ancillary functions, such as fail-safe features.

- 25 Therefore there is a need to incorporate logic integrated circuits and power transistors into a single package module, which is ideally adapted to be mounted on or in close proximity to the electric motor.

A problem with existing combined logic/power packages is that the high power
30 requirements of the high-sided switch do not easily facilitate integration with low power logic integrated circuits. The high currents involved preclude the use of conventional wire bond techniques, and the thermal management of heat dissipation presents further problems.

- 35 This invention seeks to provide an electronic package assembly which mitigates the above mentioned disadvantages.

Summary of the Invention

According to the present invention there is provided an electronic package assembly
5 comprising: a plurality of semiconductor devices, each having a first side with a plurality
of conductive pads, at least two of the plurality of devices being vertical power transistor
devices having a second side opposite the first side, the second side having further
conductive pads; a printed circuit substrate, having a plurality of printed circuit patterns
10 bonded to the conductive pads of the first sides of the plurality of semiconductor devices,
and arranged to provide logic interconnections between the plurality of semiconductor
devices; and, a leadframe including leads which provide external connections for the
package assembly, and having a non-lead island portion bonded to the further conductive
pads of the second sides of the at least two vertical power transistor devices, wherein the
15 island portion of the leadframe forms a power interconnection between the at least two
vertical power transistor devices.

Preferably the leadframe further comprises a substrate lead portion, which is arranged to
connect to a further pad of the printed circuit substrate, thereby directly connecting the
leadframe to the substrate. The substrate lead portion is preferably connected to the
20 island portion of the leadframe such that the conductive pads of the second sides of the
semiconductor devices are directly electrically connected to the substrate.

Preferably a discrete electronic device is mounted directly onto the leadframe. The
leadframe preferably has contact bumps to which the electronic device is coupled.

25 The semiconductor device may be a vertical H-bridge power transistor device.
Alternatively, the semiconductor device may be a full-bridge high-sided switch
arrangement.

30 The substrate preferably has a first face having the plurality of pads, and a second face
opposite the first face to which further electronic devices are attached. Preferably the
substrate is provided with electrical vias arranged to electrically interconnect the first and
the second faces of the substrate. Preferably the substrate is also provided with thermal
vias arranged to sink heat away from the semiconductor device.

35 In this way an electronic package assembly is provided which has improved integration
and good thermal management.

Brief Description of the Drawings

5 An exemplary embodiment of the invention will now be described with reference to the drawing in which:

FIG. 1 shows a preferred embodiment of an electronic package assembly in accordance with the invention;

10

FIG. 2 shows a block schematic diagram of the assembly of FIG. 1;

FIG. 3 shows an alternative embodiment of an electronic package assembly in accordance with the invention;

15

FIG. 4 shows a block schematic diagram of the assembly of FIG. 3;

FIG. 5 shows a top and a side view of an exemplary leadframe forming part of the assembly of FIG. 1 or FIG. 3;

20

FIG. 5a shows an alternative embodiment of the side view of FIG. 5; and,

FIG. 6 shows a top and a side view of an alternative exemplary leadframe forming part of the assembly of FIG. 1 or FIG. 3.

25

Detailed Description of a Preferred Embodiment

Referring to FIG. 1, there is shown an electronic package assembly 5 comprising double-sided leadless components (10, 14, 20) a printed circuit substrate 30, a leadframe comprising first (50) second (51) and third (52) elements and other electronic components (60, 70).

The substrate 30 is a multi-layered substrate of dielectric material and has top and bottom faces. The top face has a first set of printed circuit patterns 31-39, which facilitate connection of the substrate 30 to the double-sided leadless components (10, 14, 20) and also to the selected elements of the leadframe (50 and 52) to be further described below.

The substrate 30 also has a second set of printed circuit patterns 40-42 on the bottom face thereof. These second patterns 40-42 facilitate connection of the substrate 30 to the other electronic components (60, 70) which may be single or multiple packaged components.

5 The first component 60 may be a packaged integrated circuit having electrical terminals 61 and 62 in the form of leads, and the second component 70 may be discrete device having electrical terminals 71 and 72 in the form of edge connectors.

10 The substrate also has a number of conductive vertical vias (43-47) which provide electrical and thermal paths between the top and the bottom faces of the substrate 30.

The double-sided leadless components (10, 14, 20) comprise first 10 and second 14 power switching transistors and an integrated circuit 20.

15 The first power switching transistor 10 may be a metal-oxide field effect transistor (MOSFET) or a bipolar transistor, and has a first electrode 11 (drain electrode) in the form of a pad located on an upper face and second and third electrodes 12 and 13 (source and gate electrodes respectively) in the form of pads located on a lower face. The second and third electrodes 12 and 13 form pads which are bonded via flip-chip solder bumps (of low thermal and electrical resistivity) to the printed circuit patterns 34 and 35 respectively
20 of the substrate 30.

The second power switching transistor 14, which may also be a MOSFET or a bipolar transistor, has a first electrode 15 (drain electrode) in the form of a pad located on an upper face and second and third electrodes 16 and 17 (source and gate electrodes
25 respectively) in the form of pads located on a lower face. The second and third electrodes 16 and 17 are bonded to the printed circuit patterns 33 and 32 respectively of the substrate 30.

30 In this way the first and second power switching transistors 10 and 14 respectively have vertical current paths between the upper and the lower faces (between drain and source electrodes).

The integrated circuit 20 may contain logic circuitry or similar, and has a lower face with pads 21 to 26 which are bonded to the printed circuit patterns 35, 32, 36 to 39
35 respectively. An optional further pad 27 may be provided on an upper face, to be further described below.

The leadframe is a plurality of unsupported (i.e. non-substrate supported) metal leads, including first (50) second (51) and third (52) elements. The first element 50 connects the printed circuit pattern 33 to the pad of the drain electrode 11 of the first power switching transistor 10 via bonds at both ends. Since the first element 50 does not form an external pin connection, it is regarded as an 'island' portion of the leadframe. The second element 51 has a first arm bonded to the further pad 27 of the integrated circuit 20, and a second arm bonded to the pad forming the drain electrode 15 of the second power switching transistor 14. The first and second arms of the second element 51 are connected in a section of the assembly 5 which is not shown. The third element 52 is bonded to the printed circuit pattern 31 of the substrate 30. The second element 51 and the third element 52 of the leadframe form power supply and ground terminals respectively (via external pins, not shown) and they are regarded as 'lead' portions.

Further circuit elements may be provided which are directly bonded to the leadframe. An example is shown in the form of component 80, which is attached between the first element 50 and the second element 51 of the leadframe 30.

Referring now also to FIG. 2, there is shown a block schematic diagram of the electronic package assembly 5, where each element of FIG. 2 has the same number as the corresponding of the assembly 5 of FIG. 1, with the exception of leads 63, 64 and 65, (which occupy a different plane of assembly 5 from that shown in FIG. 1) and component 80, which is exemplary only in FIG. 1 and therefore not shown in FIG. 2.

The integrated circuit 20, (which may be bare die, as illustrated) has various connections formed by the pads 21 to 26 and printed circuit patterns 35, 32, 36 to 39. In particular the printed circuit patterns 35 and 32 connect the integrated circuit 20 to the first and second power switching transistors 10 and 14 respectively.

Similarly the electronic component 60 (which may be a packaged integrated circuit, as illustrated) has various connections formed by the leads 61 to 65.

FIG. 2 also shows further optional power transistor stages (or branches) which could easily be formed in the assembly 5.

The first (drain) electrodes 11 and 15 of the first and second power switching transistors 10 and 14 respectively and those of the further optional power transistor stages, are

arranged to convey a large amount of current during operation, and the leadframe to which they are attached is specifically arranged to provide high current capacity.

5 In this way the PCB 30 provides logic interconnects for the assembly 5, and the leadframe provides power interconnects as well as external connections.

Referring now also to FIG. 3 and FIG. 4, there is shown an alternative arrangement of the assembly 5, having the same components with the same reference numerals. In this alternative arrangement, the first element 50 of the leadframe 30 is not arranged to
10 connect the printed circuit pattern 33 to the drain electrode (pad 11) of the first power switching transistor 10. In this way a high-sided switch is formed instead of a bridge.

Referring now also to FIG. 5, there is shown a top view and a side view of a physical leadframe arrangement 100, having a substrate 130, on which a double-sided leadless
15 semiconductor device 110 is mounted. Pads 112 and 113 of the semiconductor device 110, which are only shown in the top view, connect the semiconductor device 110 to 'island' portions 152 and 153 respectively of a leadframe. A further portion 157 of the leadframe, which is integral to portions 152 and 153, provides a vertical connection to the substrate 130. A stub portion 158 provides yet another connection of the leadframe,
20 which may be to a further device, a further substrate, or to the substrate 130.

In an alternative embodiment illustrated in FIG. 5a, the further portion 157 of the substrate is replaced by a solder ball 159, which provides a connection to the substrate
25 130.

A further double-sided leadless semiconductor device 120 is also mounted on the substrate 130. Pads 114 and 115 of the semiconductor device 120, which are only shown in the top view, connect the semiconductor device 120 to portions 154 and 155
30 respectively of the leadframe. The portions 154 and 155 have pin protrusions which extend beyond an encapsulation 140 (shown by the dashed line of the side view), such that the pin protrusions provide external connections for the devices 110 and 120.

Referring now also to FIG. 6, there is shown an alternative leadframe arrangement 200, which is identical to the arrangement 100 of FIG. 5 except that the leadframe portions
35 154 and 155 have been replaced with raised leadframe pads 164 and 165. These pads 164 and 165 extend beyond the encapsulation 140, as shown by the dashed line of the side

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view, and hence provide an alternative form of external connection for the devices 110 and 120.

5 It will be appreciated that further alternative embodiments to those described above are possible. For example, it is envisaged that two or more printed circuit substrates could be incorporated into the assembly 5, using flip-chip techniques with double-sided components to replace the components 60 and 70.

10 Furthermore other combinations of interconnections and leads of the leadframes shown above are possible.

Claims

1. An electronic package assembly, comprising:
5 a plurality of semiconductor devices, each having a first side with a plurality of conductive pads, at least two of the plurality of devices being vertical power transistor devices having a second side opposite the first side, the second side having further conductive pads;
a printed circuit substrate, having a plurality of printed circuit patterns bonded to the
10 conductive pads of the first sides of the plurality of semiconductor devices, and arranged to provide logic interconnections between the plurality of semiconductor devices; and,
a leadframe including leads which provide external connections for the package assembly, and having a non-lead island portion bonded to the further conductive pads of the second sides of the at least two vertical power transistor devices,
15 wherein the island portion of the leadframe forms a power interconnection between the at least two vertical power transistor devices.
2. The assembly of claim 1 wherein the leadframe further comprises a substrate lead portion, which is arranged to connect to a further pad of the printed circuit substrate,
20 thereby directly connecting the leadframe to the substrate.
3. The assembly of claim 2 wherein the substrate lead portion is connected to the island portion of the leadframe such that the conductive pads of the second sides of the semiconductor devices are directly electrically connected to the substrate.
25
4. The assembly of claim 1 wherein a discrete electronic device is mounted directly onto the leadframe.
5. The assembly of claim 4 wherein the leadframe has contact bumps to which the
30 electronic device is coupled.
6. The assembly of any preceding claim wherein the at least two semiconductor devices form a vertical H-bridge power transistor arrangement.
- 35 7. The assembly of any preceding claim the at least two semiconductor devices form a full-bridge high-sided switch arrangement.

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8. The assembly of any preceding claim wherein the substrate has a first face having the plurality of pads, and a second face opposite the first face to which further electronic devices are attached.

5 9. The assembly of claim 8 wherein the substrate is provided with electrical vias arranged to electrically interconnect the first and the second faces of the substrate.

10. The assembly of any preceding claim wherein the substrate is provided with thermal vias arranged to sink heat away from the semiconductor device.

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INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

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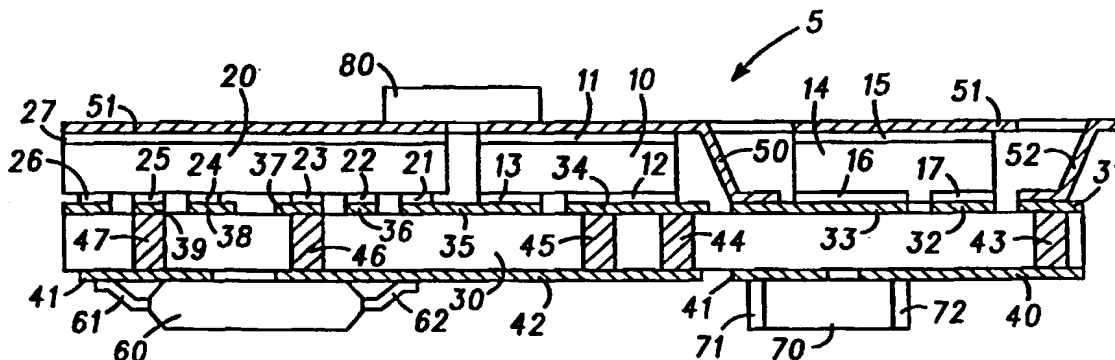
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(81) Designated States: US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

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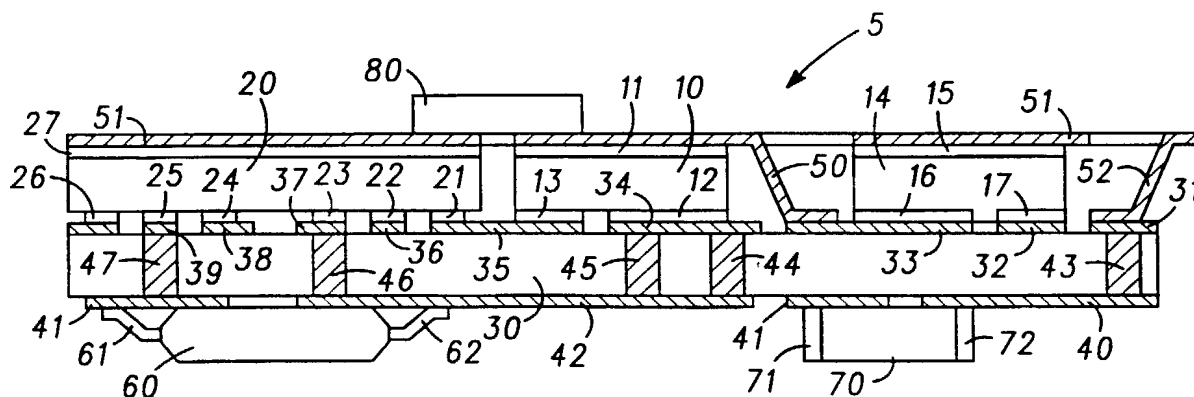
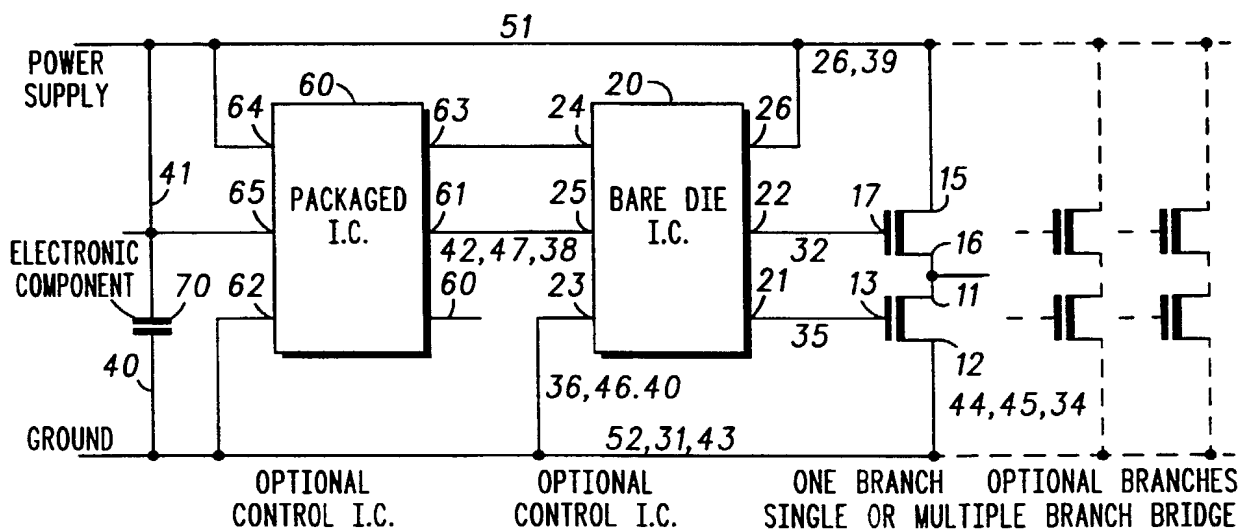
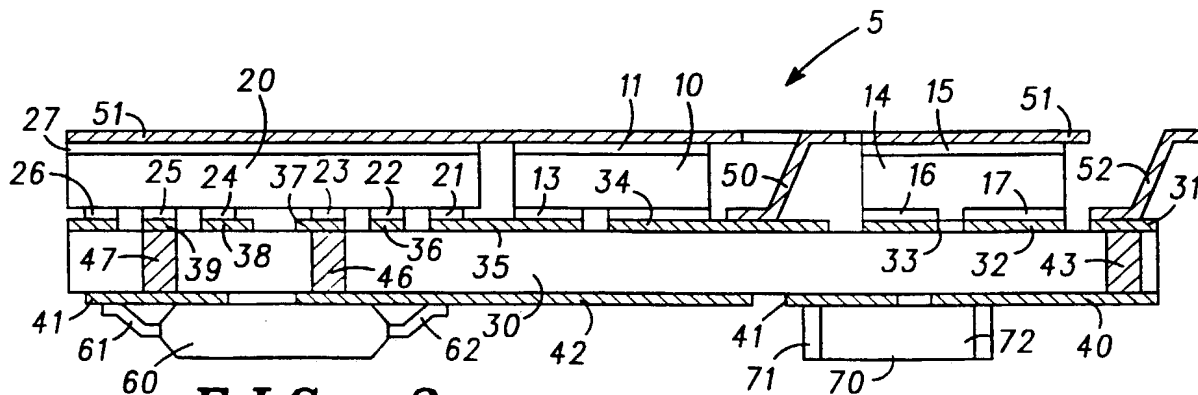
(54) Title: ELECTRONIC PACKAGE ASSEMBLY



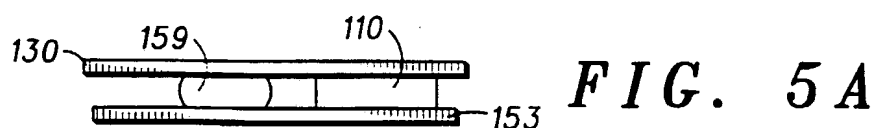
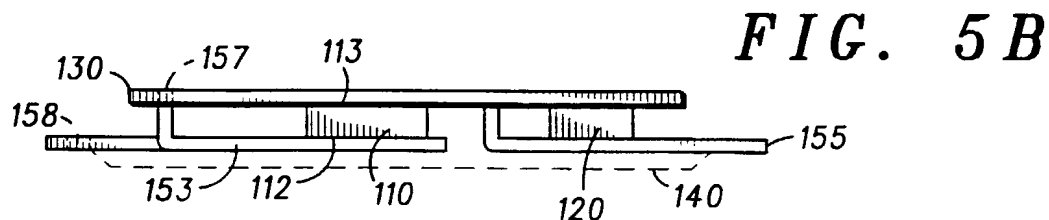
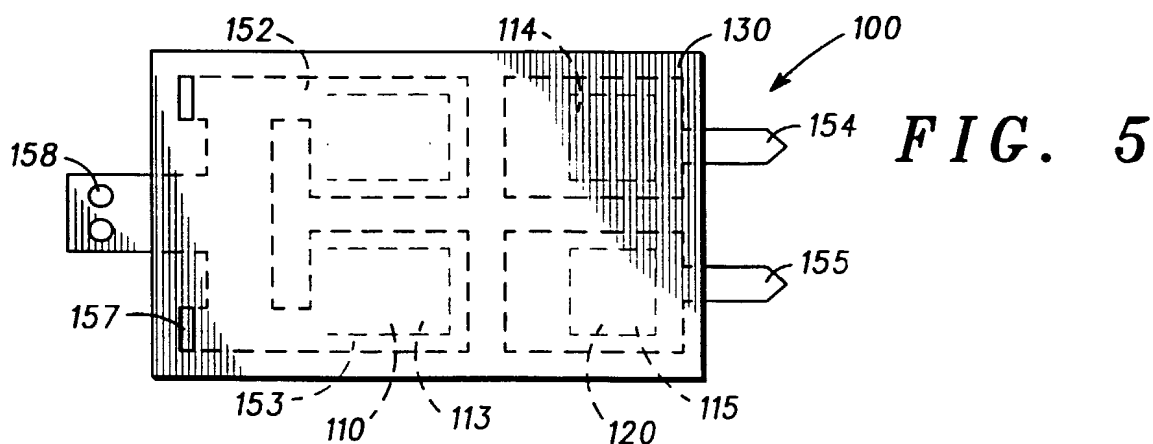
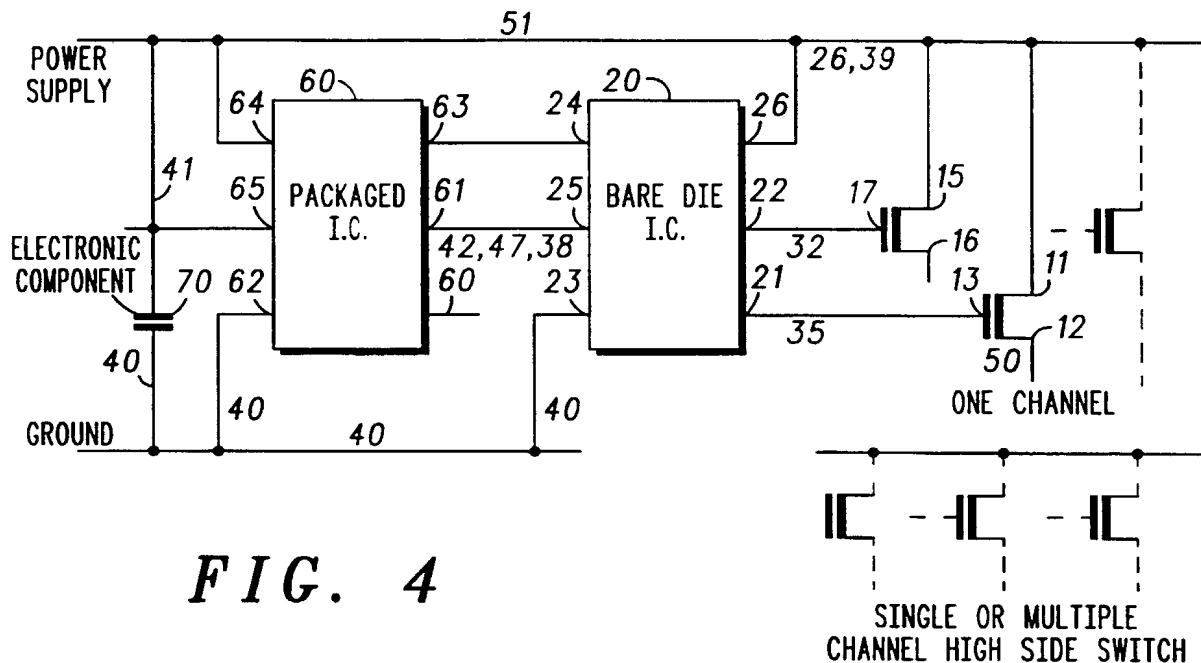
(57) Abstract

An electronic package assembly includes a number of semiconductor devices with first and second sides. A printed circuit substrate has a number of printed circuit patterns bonded to conductive pads of the first sides of the devices. A metal leadframe includes leads which provide external connections for the package assembly, and also includes a non-lead island portion bonded to conductive pads of the second sides of the devices. In this way the island portion of the leadframe forms an interconnection between the second sides of the devices.

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**FIG. 1****FIG. 2****FIG. 3**

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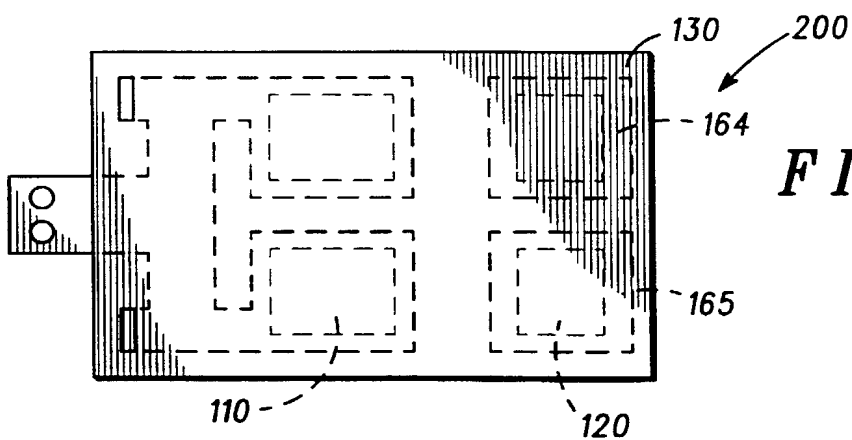


FIG. 6

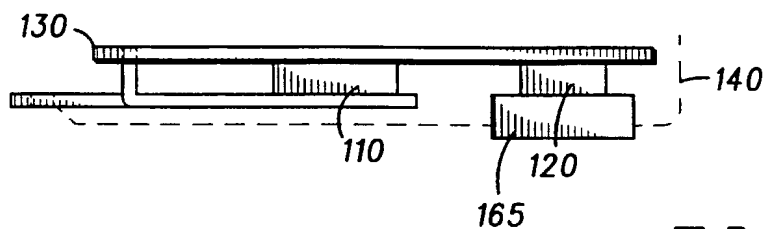


FIG. 6A

COMBINED DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION

Attorney Docket SC0704EM

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below), or an original, first and joint inventor (if plural names are listed below), of the subject matter which is claimed and for which a patent is sought on the invention entitled ELECTRONIC ASSEMBLY PACKAGE, the specification of which is attached hereto unless the following box is checked:

☒ Application was filed on 21 June 1999
as Application No. PCT/EP99/04291
and was amended on _____

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)	Priority Claimed
<u>9813888.6</u> <u>United Kingdom</u> <u>27 June 1998</u>	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
(Number) (Country) (Day/Month/Year Filed)	
_____	<input type="checkbox"/> Yes <input type="checkbox"/> No
(Number) (Country) (Day/Month/Year Filed)	

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

_____	_____
(Application Number)	(Filing Date)
_____	_____
(Application Number)	(Filing Date)

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

_____	_____	_____
(Application Number)	(Filing Date)	(Status - patented, pending, abandoned)
_____	_____	_____
(Application Number)	(Filing Date)	(Status - patented, pending, abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

1-00

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3-00

FULL NAME OF THIRD INVENTOR: FIRST MIDDLE LAST	INVENTOR'S SIGNATURE	DATE: (SPELL OUT MONTH)
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POST OFFICE ADDRESS:		
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